

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
-60V	8mΩ@-10V	-75A
	10mΩ@-4.5V	



合肥矽普半导体

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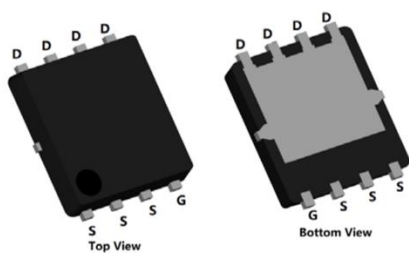
Feature

- Fast switching speed
- Surface mount package
- ROHS Compliant & Halogen-Free
- Advanced Split Gate Trench Technology
- 100% Single Pulse avalanche energy Test

Applications

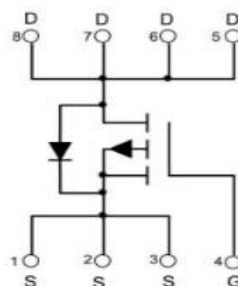
- DC-DC Converters.
- Motor Control.

Package

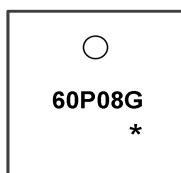


PDFN5×6-8L

Circuit diagram



Marking



60P08G
*

:Device Code
:Month Code

Order Information

Device	Package	Unit/Tape
SP60P08GNK	PDFN5×6-8L	5000

Absolute maximum ratings (Ta=25°C, unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V _{DSS}	-60	V
Gate-Source Voltage	V _{GSS}	±20	V
Continuous Drain Current (Tc=25°C)	I _D	-75	A
Continuous Drain Current (Tc=100°C)	I _D	-50	A
Pulse Drain Current Tested	I _{DM}	-300	A
Single pulsed avalanche energy ¹	EAS	453	mJ
Maximum Power Dissipation (Tc=25°C)	P _D	110	W
Maximum Power Dissipation (Tc=100°C)	P _D	44	W
Thermal Resistance-Junction to Case	R _{θJC}	1.1	°C/W
Maximum Junction Temperature	T _J	-55 to 150	°C
Storage Temperature Range	T _{STG}	-55 to 150	°C

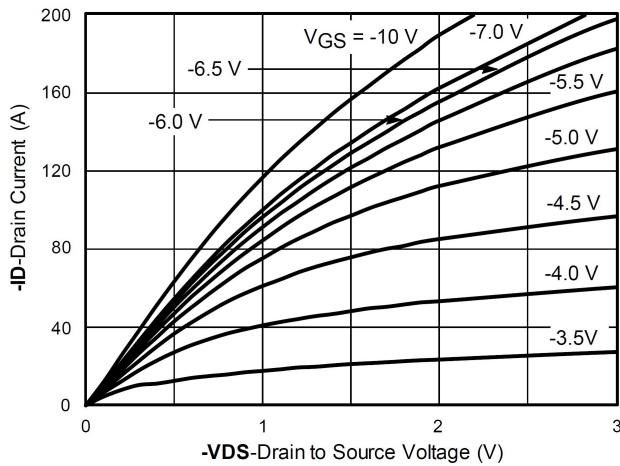
Electrical characteristics (Ta=25°C, unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	VGS=0V , ID=-250uA	-60	-	-	V
Drain-Source Leakage Current	I _{DSS}	VDS=-48V , VGS=0V , TJ=25℃	-	-	-1	uA
Gate-Source Leakage Current	I _{GSS}	VGS=±20V , VDS=0V	-	-	±100	nA
Gate Threshold Voltage	V _{GS(th)}	VGS=VDS , ID =-250uA	-1.6	-2.0	-2.5	V
Static Drain-Source On-Resistance	R _{DS(ON)}	VGS=-10V , ID=-15A	-	8	10	mΩ
		VGS=-4.5V , ID=-15A	-	10	13.5	
Gate Resistance	R _G	VDS=-30V , VGS=0V , f=1MHz	-	2.1	-	Ω
Dynamic characteristics						
Input Capacitance	C _{iss}	VDS=-30V , VGS=0V , f=1MHz	-	3790	-	pF
Output Capacitance	C _{oss}		-	913	-	
Reverse Transfer Capacitance	C _{rss}		-	19	-	
Total Gate Charge	Q _g	VDS=-30V , VGS=-10V , ID=-15A	-	56	-	nC
Gate-Source Charge	Q _{gs}		-	10	-	
Gate-Drain Charge	Q _{gd}		-	8.6	-	
Gate Plateau Voltage	V _{plateau}		-	-3.6	-	
Switching Characteristics						
Turn-On Delay Time	T _{d(on)}	VDD=-30V , VGS=-10V , RG=3Ω , ID=-15A	-	15	-	ns
Rise Time	T _r		-	17	-	
Turn-Off Delay Time	T _{d(off)}		-	46	-	
Fall Time	T _f		-	29	-	
Diode Characteristics						
Diode Forward Voltage	V _{SD}	VGS=0V , IS=-1A , TJ=25℃	-	-	-1.2	V
Diode Continuous Current	I _S		-	-	-75	A
Reverse recover time	T _{rr}	IS=-15A , di/dt=100A/us , TJ=25℃	-	48	-	ns
Reverse recovery charge	Q _{rr}		-	56	-	nC

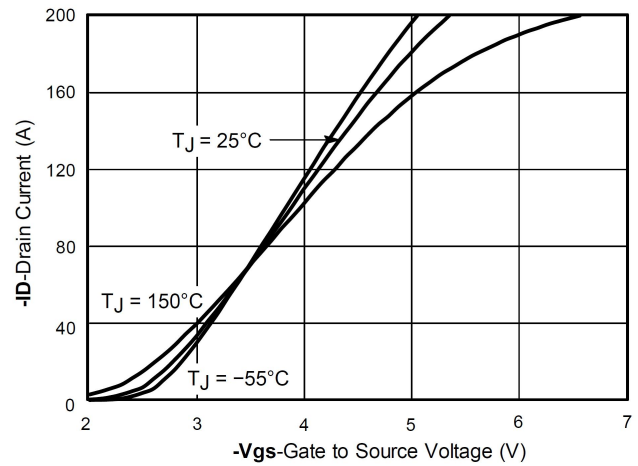
Note:

1. The test condition is VDD=-30V, VGS=-10V, L=0.5mH, RG=25Ω

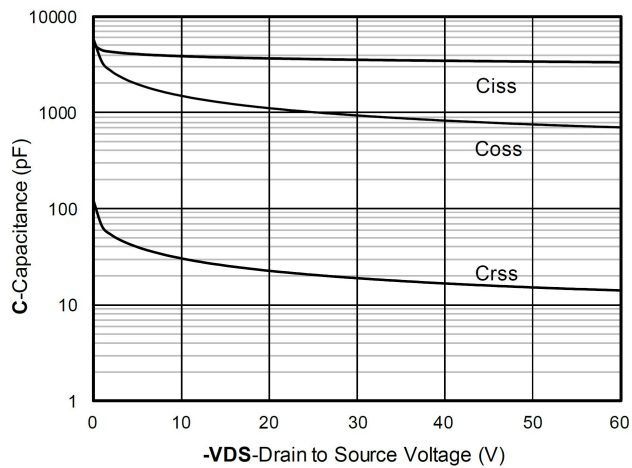
Typical Characteristics



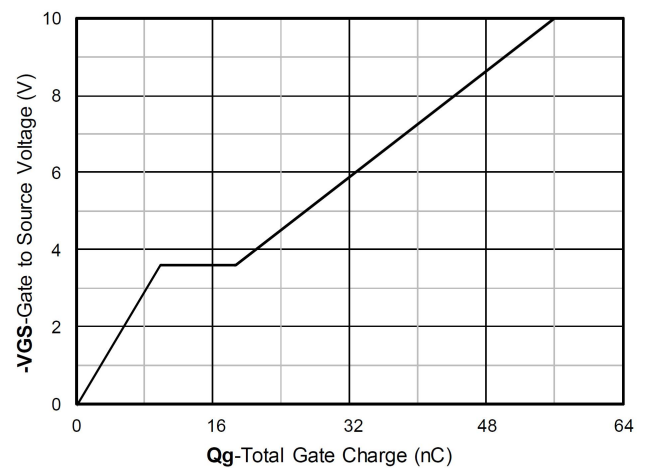
Output Characteristics



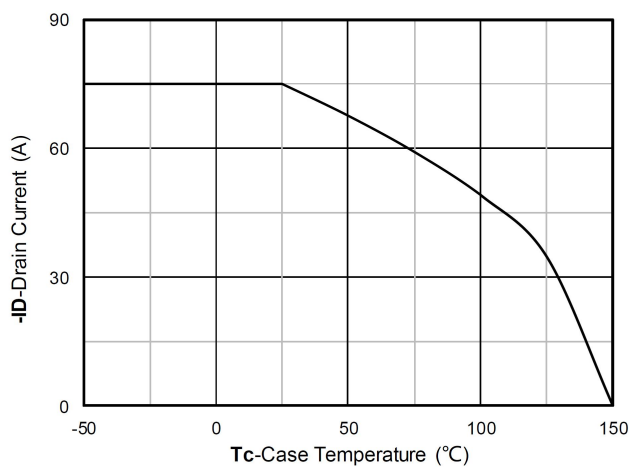
Transfer Characteristics



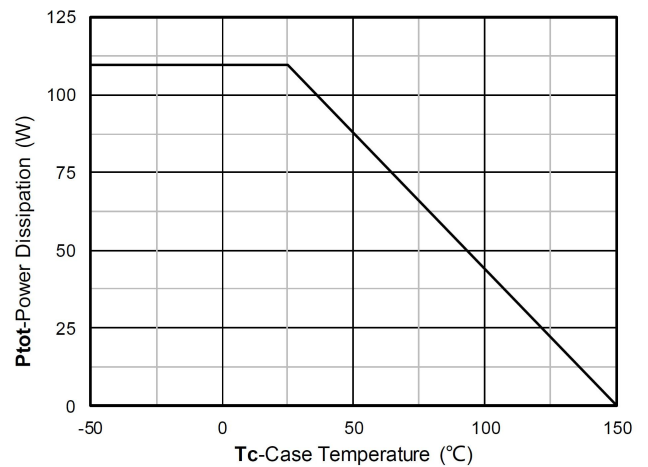
Capacitance Characteristics



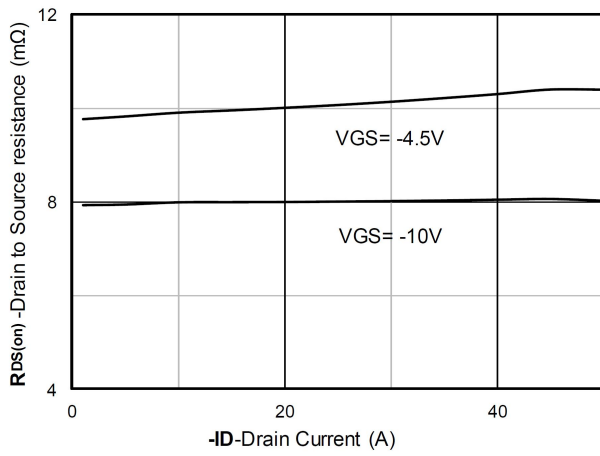
Gate Charge



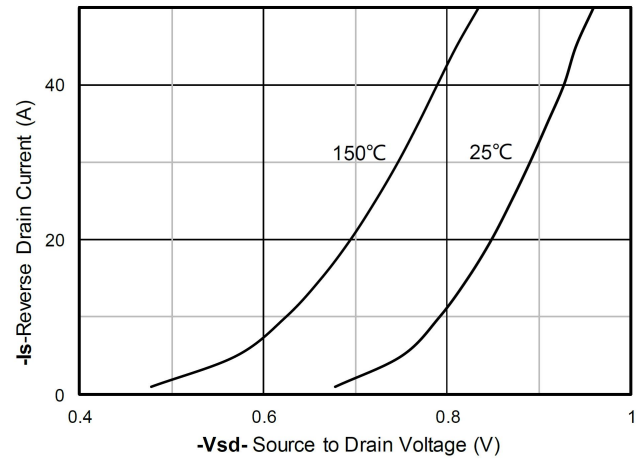
Current dissipation



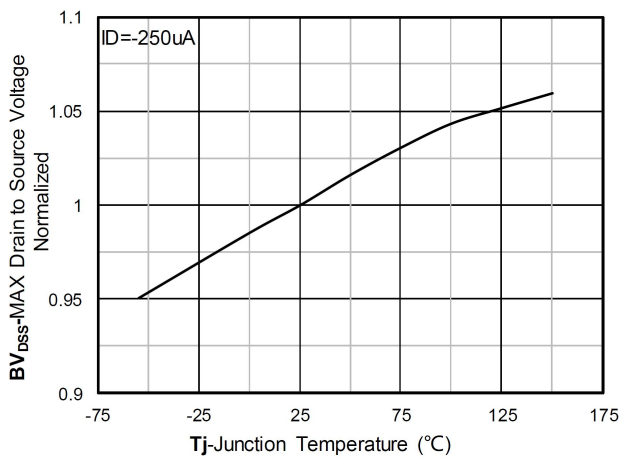
Power dissipation



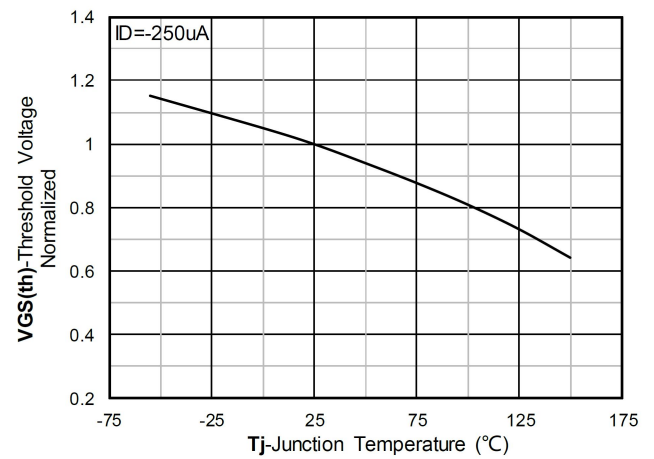
$R_{DS(on)}$ VS Drain Current



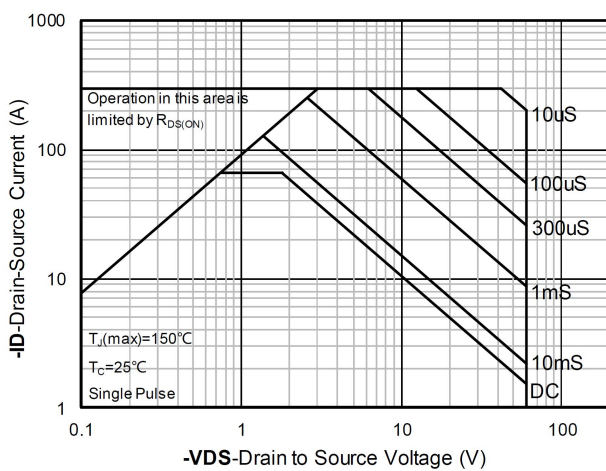
Forward characteristics of reverse diode



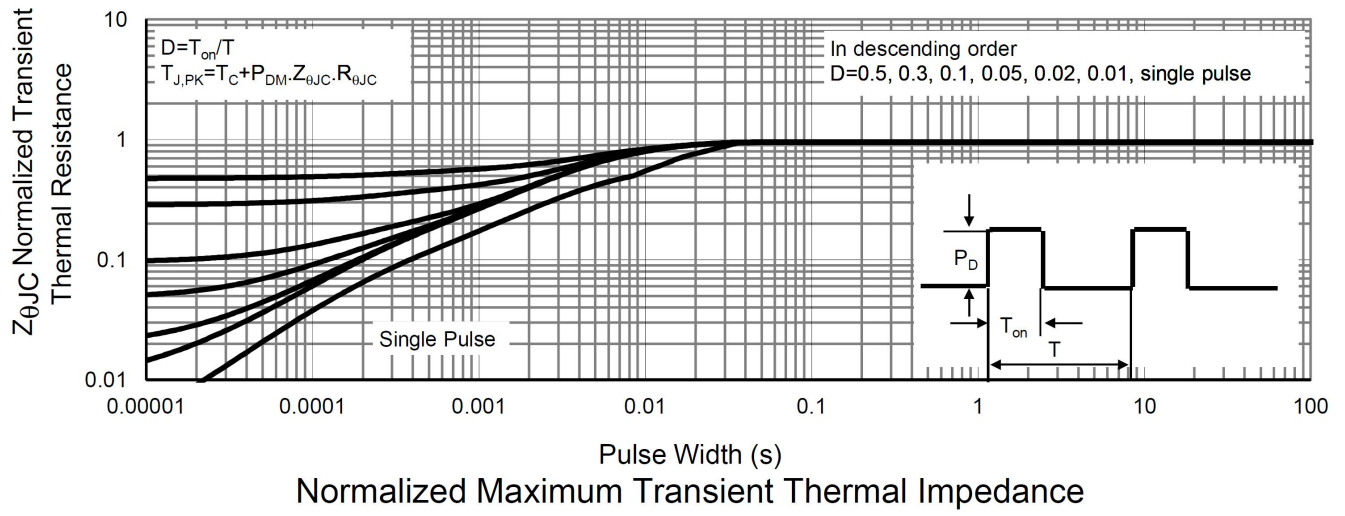
Normalized breakdown voltage



Normalized Threshold voltage

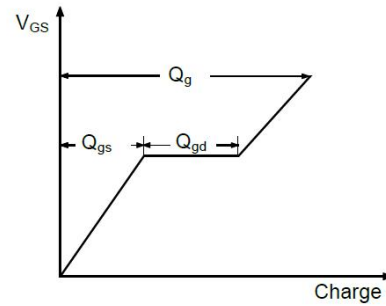
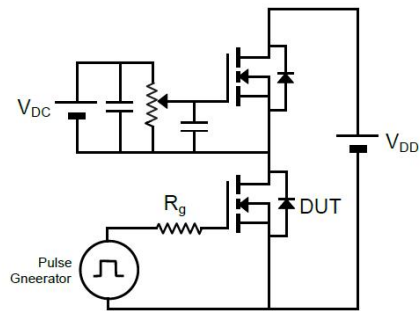


Safe Operation Area

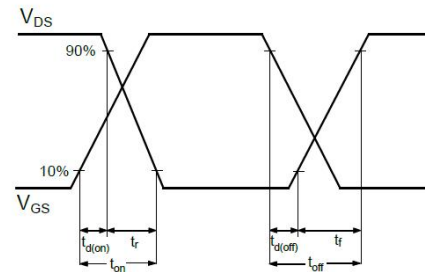
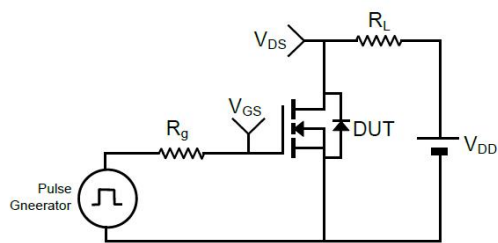


Test Circuit

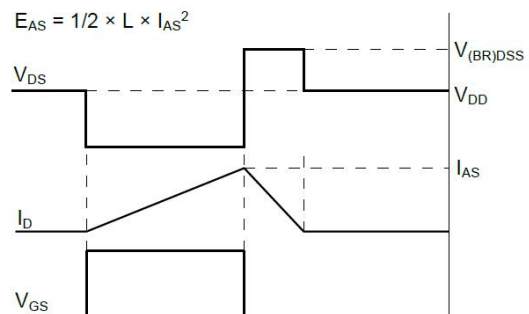
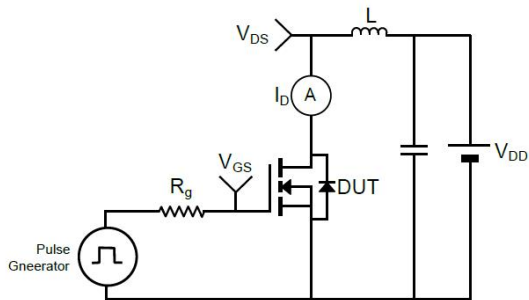
Gate Charge



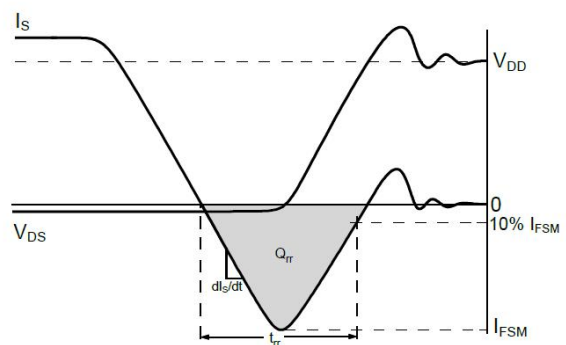
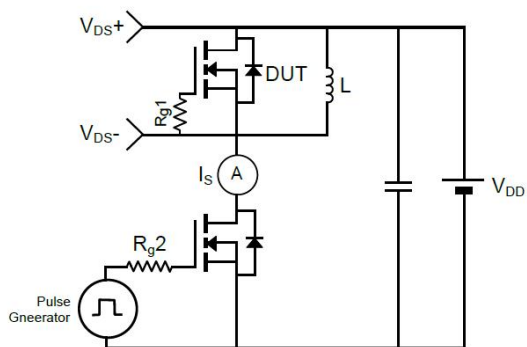
Resistive Load Switching Time



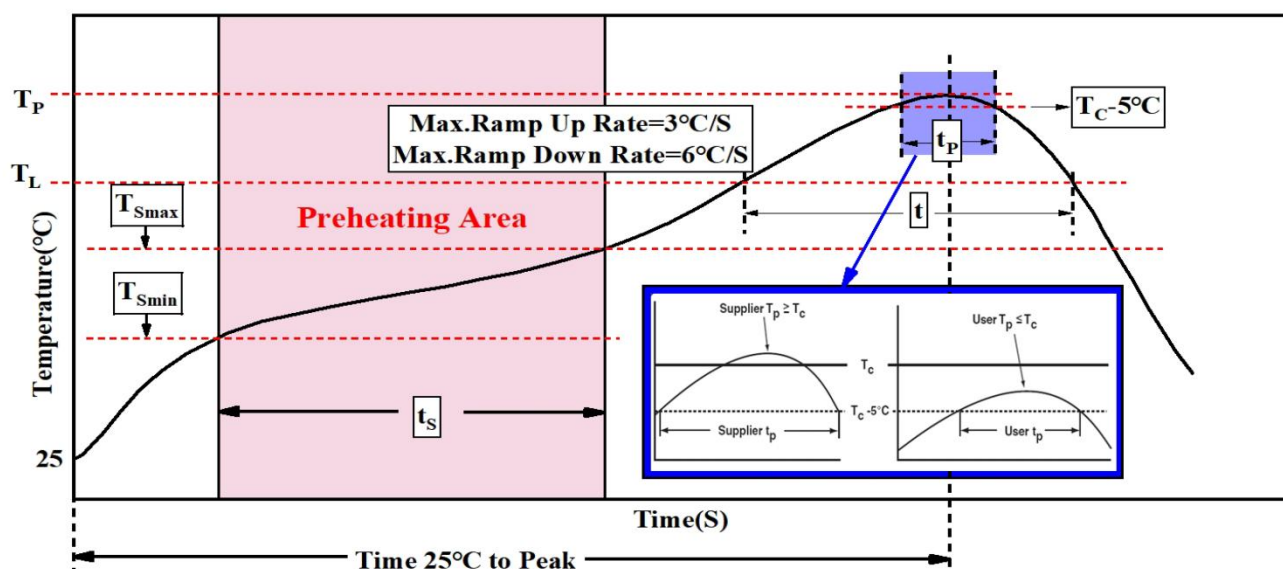
Un-clamped Inductive Load Switching



Drain-Source Body Diode Reverse Recovery



Temperature Profile for IR Reflow Soldering



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat & Soak		
Temperature min (T_{Smin})	100°C	150°C
Temperature max (T_{Smax})	150°C	200°C
Time (T_{Smin} to T_{Smax}) (t_s)	60-120 seconds	60-120 seconds
Average ramp-up rate (T_{Smax} to T_P)	3 °C/second max.	3°C/second max.
Liquidous temperature (T_L)	183 °C	217°C
Time at liquidous (t_L)	60-150 seconds	60-150 seconds
Peak package body Temperature e (T_P)*	See Classification Temp in table 1	See Classification Temp in table 2
Time (t_P)** within 5°C of the specified classification temperature (T_C)	20** seconds	30** seconds
Average ramp-down rate (T_P to T_{Smax})	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
* Tolerance for peak profile Temperature (T_P) is defined as a supplier minimum and a user maximum. ** Tolerance for time at peak profile temperature (t_P) is defined as a supplier minimum and a user maximum		

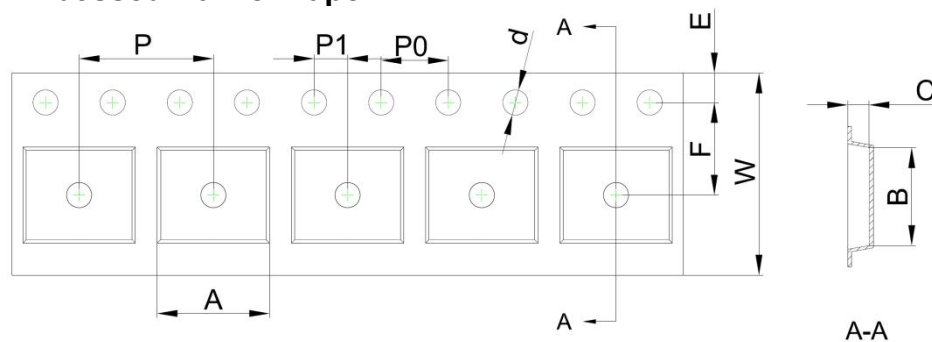
Table 1. SnPb Eutectic Process – Classification Temperatures (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

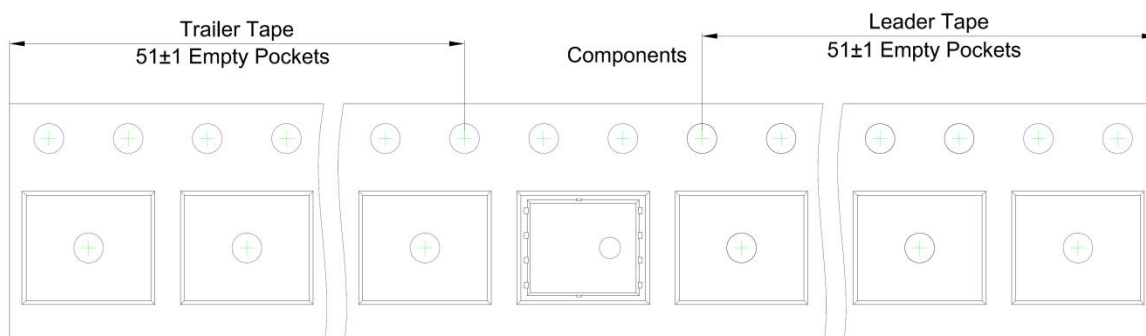
PDFN5X6-8L Embossed Carrier Tape



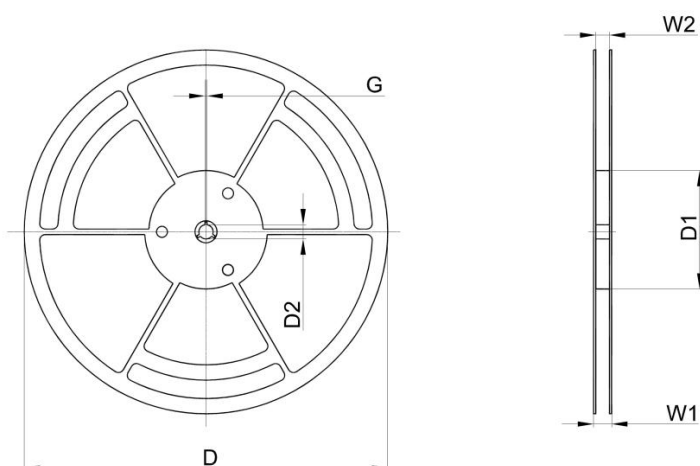
Dimensions are in millimeter

Pkg type	A	B	C	d	E	F	P0	P	P1	W
PDFN5X6-8L	6.30	5.30	1.10	Φ1.50	1.75	5.50	4.00	8.00	2.00	12.00

PDFN5X6-8L Tape Leader and Trailer



PDFN5X6-8L Reel

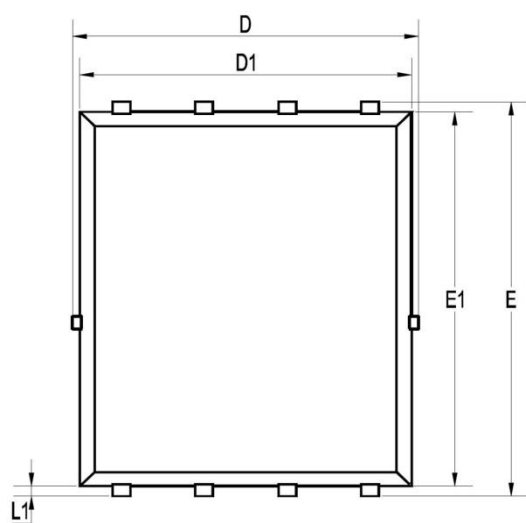


Dimensions are in millimeter

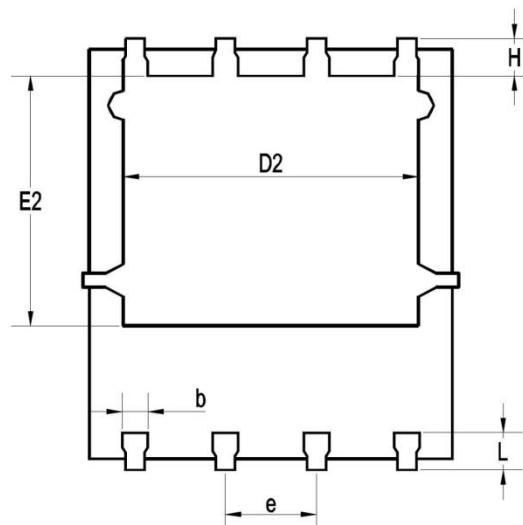
Reel Option	D	D1	D2	G	W1	W2
13"Dia	Ø330.00	100.00	13.00	1.90	17.60	12.40

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)
5,000 pcs	13 inch	5,000 pcs	340×336×29	50,000 pcs	353×346×365

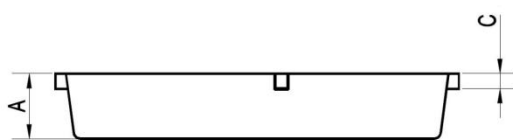
PDFN5X6-8L Package Information



Top View
[顶视图]



Bottom View
[背视图]



Side View
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.120	0.035	0.044
b	0.330	0.510	0.013	0.020
C	0.110	0.340	0.004	0.013
D	4.700	5.260	0.185	0.207
D1	4.700	5.100	0.185	0.201
D2	3.560	4.500	0.140	0.177
E	5.750	6.250	0.226	0.246
E1	5.600	6.000	0.220	0.236
E2	3.180	3.660	0.125	0.144
e	1.170	1.370	0.046	0.054
L	0.350	0.710	0.014	0.028
L1	0.060	0.200	0.002	0.008
H	0.350	0.710	0.014	0.028